



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE  
BEFORE THE BOARD OF PATENT APPEALS AND INTERFERENCES

GARY P. MORRISON ET AL.

Serial No. 10/034,827 (TI-31373)

Filed January 3, 2002

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Art Unit 2827

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**BRIEF ON APPEAL**

**REAL PARTY IN INTEREST**

The real party in interest is Texas Instruments Incorporated, a Delaware corporation with offices at 7839 Churchill Way, Dallas, Texas 75251.

**RELATED APPEALS AND INTERFERENCES**

There are no known related appeals and/or interferences.

**STATUS OF CLAIMS**

This is an appeal of claims 2, 4 to 10, 12, 15, 17, 18, 20 and 23, all of the rejected claims. No claims have been allowed. Please charge any costs to Deposit Account No. 20-0668.

TI-31373-1

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